

Abstract

A resist film is applied onto an entire surface and subjected to patterning substantially in the same form as an opening to bury the resist film inside the opening. Where a
5 positive resist is used, a photomask having a light-shielding portion whose region is smaller than the opening is used, or where a negative resist is used, a photomask having a light transmitting portion whose region is smaller than the opening is
10 used.